

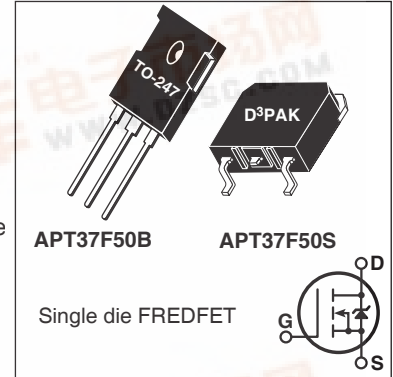


**APT37F50B**  
**APT37F50S**

500V, 37A, 0.15Ω Max,  $t_{rr} \leq 250ns$

## N-Channel FREDFET

Power MOS 8™ is a high speed, high voltage N-channel switch-mode power MOSFET. This 'FREDFET' version has a drain-source (body) diode that has been optimized for high reliability in ZVS phase shifted bridge and other circuits through reduced  $t_{rr}$ , soft recovery, and high recovery  $dv/dt$  capability. Low gate charge, high gain, and a greatly reduced ratio of  $C_{rSS}/C_{iSS}$  result in excellent noise immunity and low switching loss. The intrinsic gate resistance and capacitance of the poly-silicon gate structure help control  $di/dt$  during switching, resulting in low EMI and reliable paralleling, even when switching at very high frequency.



### FEATURES

- Fast switching with low EMI
- Low  $t_{rr}$  for high reliability
- Ultra low  $C_{rSS}$  for improved noise immunity
- Low gate charge
- Avalanche energy rated
- RoHS compliant

### TYPICAL APPLICATIONS

- ZVS phase shifted and other full bridge
- Half bridge
- PFC and other boost converter
- Buck converter
- Single and two switch forward
- Flyback

### Absolute Maximum Ratings

Symbol	Parameter	Ratings	Unit
$I_D$	Continuous Drain Current @ $T_C = 25^\circ C$	37	A
	Continuous Drain Current @ $T_C = 100^\circ C$	24	
$I_{DM}$	Pulsed Drain Current <sup>①</sup>	115	
$V_{GS}$	Gate-Source Voltage	±30	V
$E_{AS}$	Single Pulse Avalanche Energy <sup>②</sup>	780	mJ
$I_{AR}$	Avalanche Current, Repetitive or Non-Repetitive	18	A

### Thermal and Mechanical Characteristics

Symbol	Characteristic	Min	Typ	Max	Unit
$P_D$	Total Power Dissipation @ $T_C = 25^\circ C$			520	W
$R_{\theta JC}$	Junction to Case Thermal Resistance			0.24	°C/W
$R_{\theta CS}$	Case to Sink Thermal Resistance, Flat, Greased Surface		0.11		
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55		150	°C
$T_L$	Soldering Temperature for 10 Seconds (1.6mm from case)			300	
$W_T$	Package Weight		0.22		oz
			6.2		g
Torque	Mounting Torque ( TO-247 Package), 6-32 or M3 screw			10	in-lbf
				1.1	N·m

### Static Characteristics

$T_J = 25^\circ\text{C}$  unless otherwise specified

APT37F50B\_S

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$V_{BR(DSS)}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	500			V
$\Delta V_{BR(DSS)}/\Delta T_J$	Breakdown Voltage Temperature Coefficient	Reference to $25^\circ\text{C}, I_D = 250\mu A$		0.60		V/ $^\circ\text{C}$
$R_{DS(on)}$	Drain-Source On Resistance <sup>③</sup>	$V_{GS} = 10V, I_D = 18A$		0.13	0.15	$\Omega$
$V_{GS(th)}$	Gate-Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 1mA$	3	4	5	V
$\Delta V_{GS(th)}/\Delta T_J$	Threshold Voltage Temperature Coefficient			-10		mV/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 600V$ $V_{GS} = 0V$	$T_J = 25^\circ\text{C}$		250	$\mu A$
			$T_J = 125^\circ\text{C}$		1000	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS} = \pm 30V$			$\pm 100$	nA

### Dynamic Characteristics

$T_J = 25^\circ\text{C}$  unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$g_{fs}$	Forward Transconductance	$V_{DS} = 50V, I_D = 18A$		27		S
$C_{iss}$	Input Capacitance	$V_{GS} = 0V, V_{DS} = 25V$ $f = 1MHz$		5710		pF
$C_{rss}$	Reverse Transfer Capacitance			75		
$C_{oss}$	Output Capacitance			615		
$C_{o(cr)}$ <sup>④</sup>	Effective Output Capacitance, Charge Related	$V_{GS} = 0V, V_{DS} = 0V$ to 333V		355		pF
$C_{o(er)}$ <sup>⑤</sup>	Effective Output Capacitance, Energy Related			180		
$Q_g$	Total Gate Charge	$V_{GS} = 0$ to 10V, $I_D = 18A$ , $V_{DS} = 250V$		145		nC
$Q_{gs}$	Gate-Source Charge			32		
$Q_{gd}$	Gate-Drain Charge			65		
$t_{d(on)}$	Turn-On Delay Time	<b>Resistive Switching</b> $V_{DD} = 333V, I_D = 18A$ $R_G = 4.7\Omega$ <sup>⑥</sup> , $V_{GG} = 15V$		25		ns
$t_r$	Current Rise Time			29		
$t_{d(off)}$	Turn-Off Delay Time			65		
$t_f$	Current Fall Time			21		

### Source-Drain Diode Characteristics

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$I_S$	Continuous Source Current (Body Diode)	MOSFET symbol showing the integral reverse p-n junction diode (body diode)			37	A
$I_{SM}$	Pulsed Source Current (Body Diode) <sup>①</sup>				115	
$V_{SD}$	Diode Forward Voltage	$I_{SD} = 18A, T_J = 25^\circ\text{C}, V_{GS} = 0V$			1.0	V
$t_{rr}$	Reverse Recovery Time	$I_{SD} = 18A$ <sup>③</sup> $di_{SD}/dt = 100A/\mu s$ $V_{DD} = 100V$	$T_J = 25^\circ\text{C}$		250	ns
			$T_J = 125^\circ\text{C}$		450	
$Q_{rr}$	Reverse Recovery Charge	$I_{SD} = 18A$ <sup>③</sup> $di_{SD}/dt = 100A/\mu s$ $V_{DD} = 100V$	$T_J = 25^\circ\text{C}$		0.88	$\mu C$
			$T_J = 125^\circ\text{C}$		2.18	
$I_{rrm}$	Reverse Recovery Current	$I_{SD} = 18A$ <sup>③</sup> $di_{SD}/dt = 100A/\mu s$ $V_{DD} = 100V$	$T_J = 25^\circ\text{C}$		8.4	A
			$T_J = 125^\circ\text{C}$		11.8	
dv/dt	Peak Recovery dv/dt	$I_{SD} \leq 18A, di/dt \leq 1000A/\mu s, V_{DD} = 333V,$ $T_J = 125^\circ\text{C}$			20	V/ns

① Repetitive Rating: Pulse width and case temperature limited by maximum junction temperature.

② Starting at  $T_J = 25^\circ\text{C}$ ,  $L = 4.81mH$ ,  $R_G = 4.7\Omega$ ,  $I_{AS} = 18A$ .

③ Pulse test: Pulse Width < 380 $\mu s$ , duty cycle < 2%.

④  $C_{o(cr)}$  is defined as a fixed capacitance with the same stored charge as  $C_{OSS}$  with  $V_{DS} = 67\%$  of  $V_{(BR)DSS}$ .

⑤  $C_{o(er)}$  is defined as a fixed capacitance with the same stored energy as  $C_{OSS}$  with  $V_{DS} = 67\%$  of  $V_{(BR)DSS}$ . To calculate  $C_{o(er)}$  for any value of  $V_{DS}$  less than  $V_{(BR)DSS}$ , use this equation:  $C_{o(er)} = -1.33E-7/V_{DS}^2 + 3.06E-8/V_{DS} + 8.83E-11$ .

⑥  $R_G$  is external gate resistance, not including internal gate resistance or gate driver impedance. (MIC4452)

Microsemi reserves the right to change, without notice, the specifications and information contained herein.

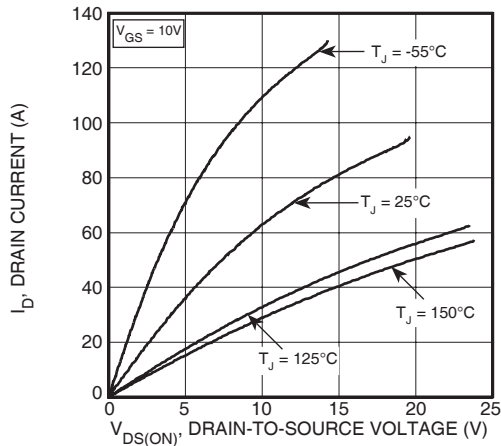


Figure 1, Output Characteristics

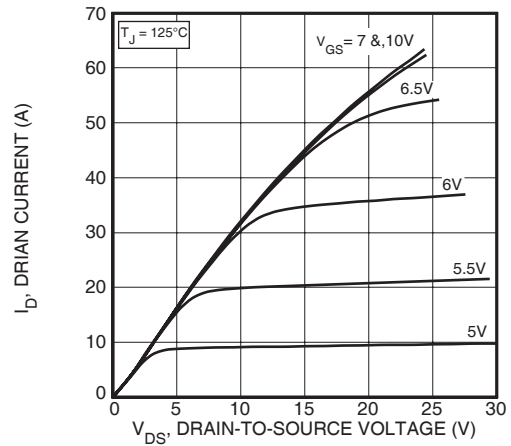


Figure 2, Output Characteristics

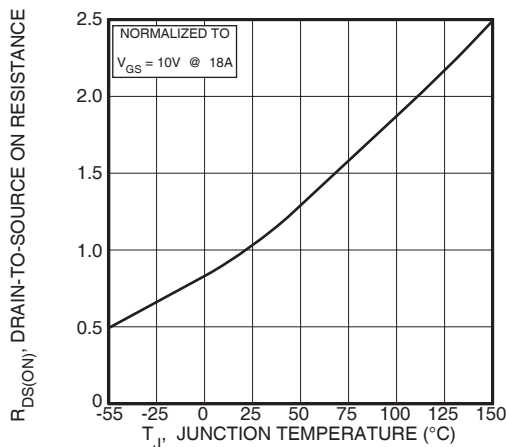


Figure 3,  $R_{DS(ON)}$  vs Junction Temperature

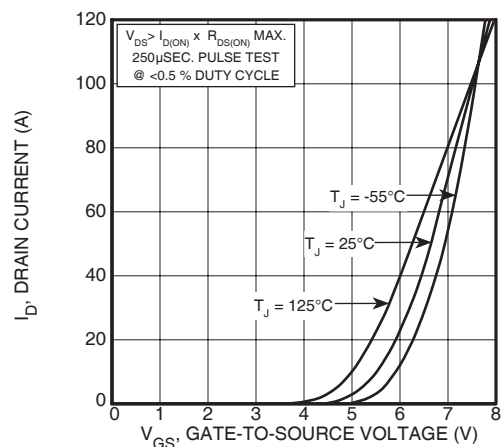


Figure 4, Transfer Characteristics

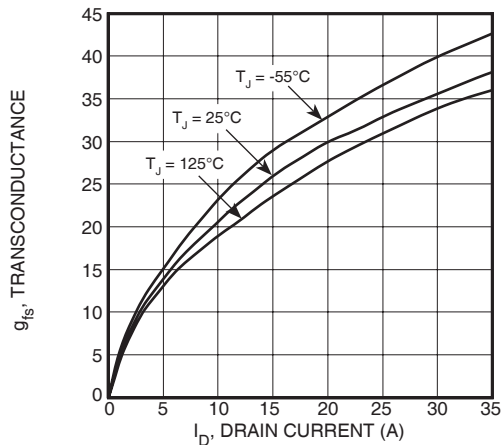


Figure 5, Gain vs Drain Current

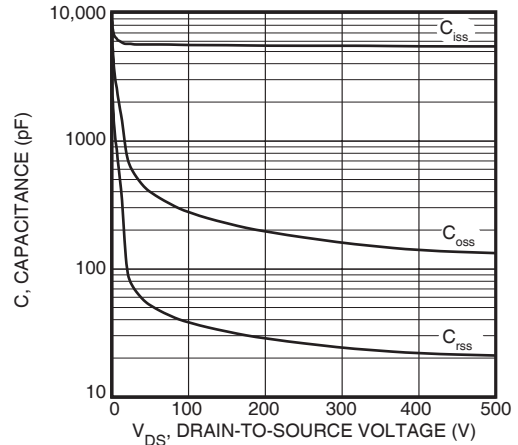


Figure 6, Capacitance vs Drain-to-Source Voltage

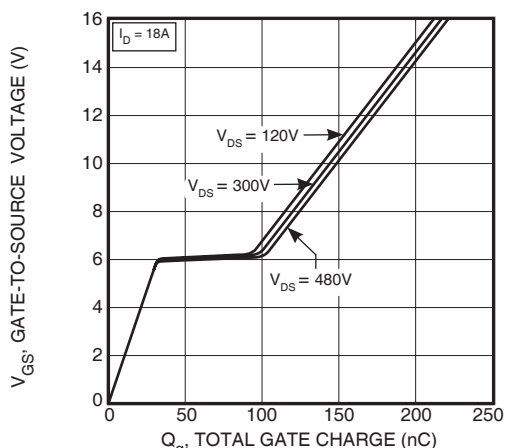


Figure 7, Gate Charge vs Gate-to-Source Voltage

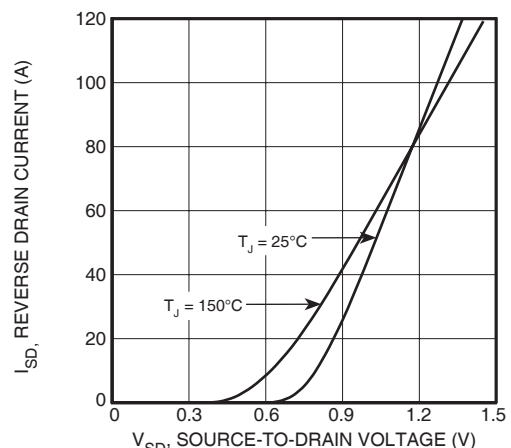


Figure 8, Reverse Drain Current vs Source-to-Drain Voltage

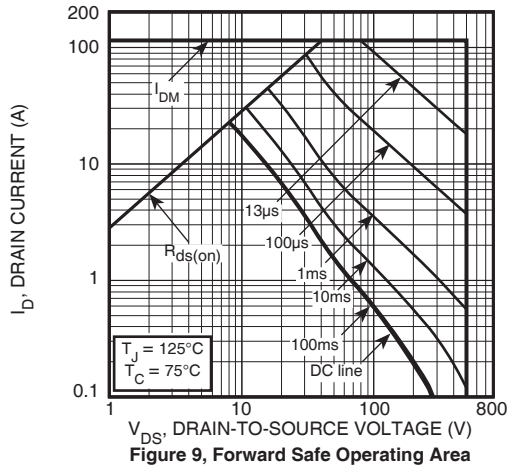


Figure 9, Forward Safe Operating Area

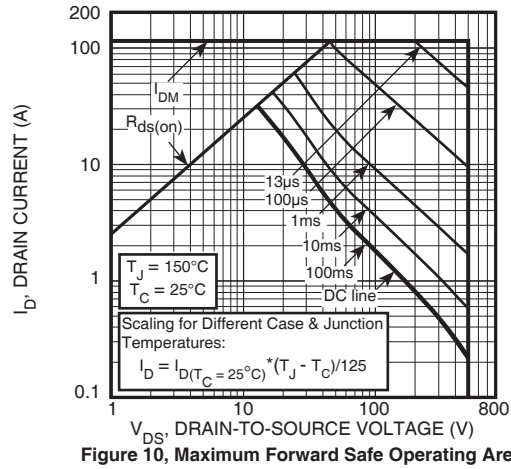
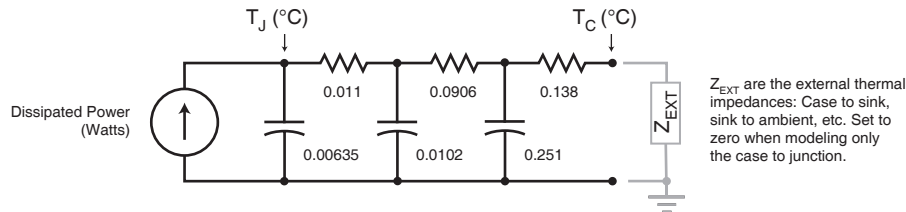


Figure 10, Maximum Forward Safe Operating Area



Z<sub>EXT</sub> are the external thermal impedances: Case to sink, sink to ambient, etc. Set to zero when modeling only the case to junction.

Figure 11, Transient Thermal Impedance Model

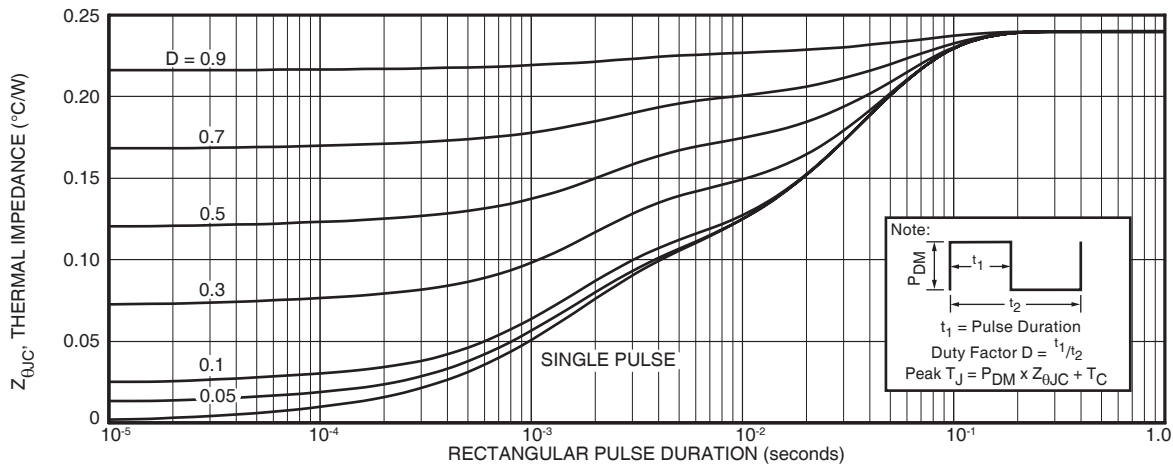
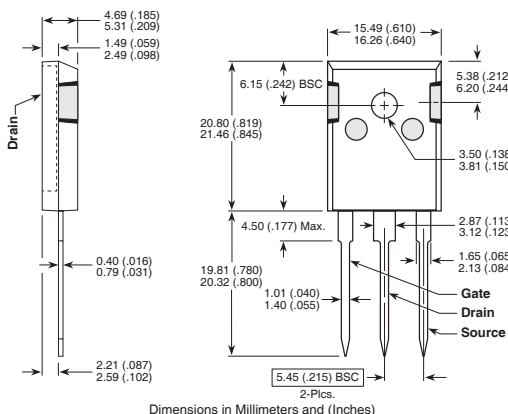


Figure 12. Maximum Effective Transient Thermal Impedance Junction-to-Case vs Pulse Duration

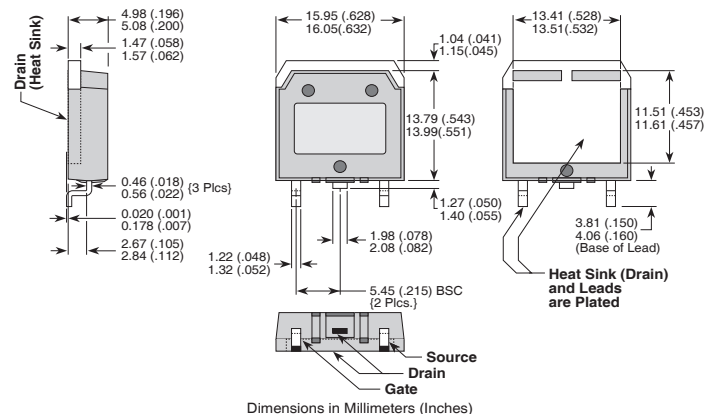
TO-247 (B) Package Outline



Dimensions in Millimeters and (Inches)

D<sup>3</sup>PAK Package Outline

Ⓜ 100% Sn Plated



Dimensions in Millimeters and (Inches)